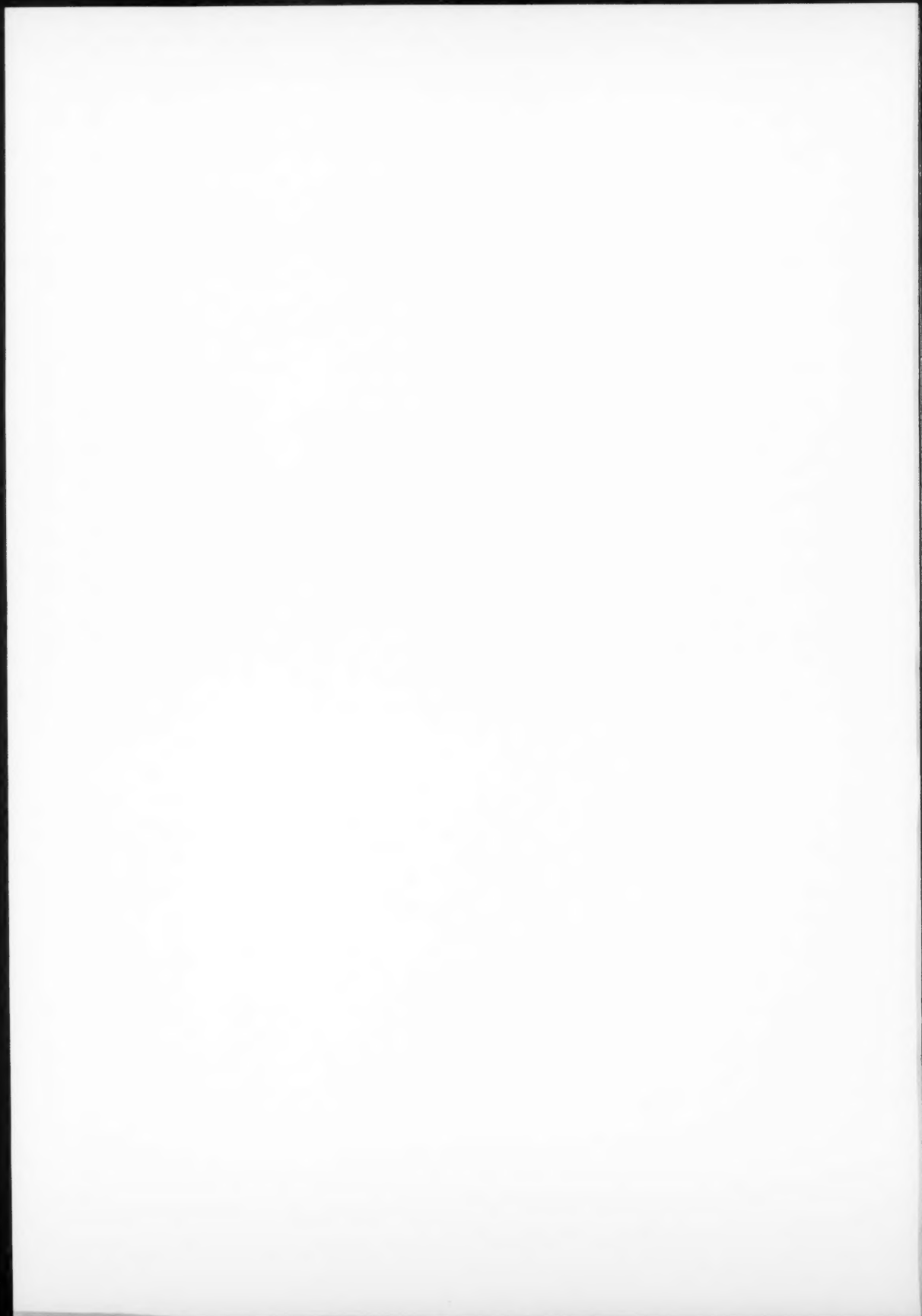




Author Index

- Adamczyk, Z., 157
Ahmadi, G., 189
Ala-Nissila, T., 209
Alava, M., 209
Asikainen, J., 209
- Bai, R., 95
Bartelt, M.C., 373
Bhattacharjee, S., 143
Bišćan, J., 115
Borkovec, M., 79
Busnaina, A.A., 3
- Chen, J.Y., 143
- Eklund, E., 11
Elimelech, M., 143
Evans, J.W., 241, 373
- Haataja, M., 209
Hannon, J.B., 373
Hart, S.C., 189
Hays, D., 11
- James, E.W., 241
- Jullien, R., 405
- Kallay, N., 115
Koper, G.J.M., 39
- Lenhoff, A.M., 125
Liu, D.-J., 241
- Majaniemi, S., 209
Matijević, E., 59
Meakin, P., 405
Mizes, H., 11
- Oberholzer, M.R., 125
Ott, M., 11
- Percus, J.K., 345
Privman, V., 231
Provatas, N., 209
- Quesnel, D.J., 3
- Ramsden, J.J., 25
Rička, J., 79
Rimai, D.S., 3
- Ryde, N.P., 59
- Schaaf, P., 255
Schmid, A.K., 373
Semmler, M., 79
Senger, B., 255
Smolić, T., 115
Soltani, M., 189
Stoldt, C.R., 373
Szyk-Warszyńska, L., 157
- Talbot, J., 287
Tarjus, G., 287
Tien, C., 95
- Van Tassel, P.R., 287
Viot, P., 287
Voegel, J.-C., 255
- Wang, J.-S., 325
Warszyński, P., 157
Weroński, P., 157
Woo Lee, J., 363
- Yuan, Y., 125





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Subject Index

- Adhesion, 11, 115
- Adhesion of particles, 59
- Adhesion rate constant, 115
- Amidine latex, 79
- Arrays, 25
- Association, 25
- Atomic force, 11
- Atomic force microscopy, 79
- Bethe lattice, 345
- Binary mixtures, 363
- Car parking, 287
- Centrifugal, 11
- Charged colloidal particles, 125
- Chemisorption, 241
- Cobalt, 373
- Colloidal films, 39
- Colloidal particles, 255
- Colloid particle deposition, 157
- Colloids, 231
- Colloid stability, 115
- Computer simulations, 405
- Continuum percolation, 209
- Convective effects in particle deposition, 157
- Copper, 373
- Deposition, 325
- Deposition equations, 95
- Deposition models, 209
- Deposition of particles, 59
- Deposition of particles of collectors, 157
- Derjaguin's approximation, 0
- Desorption, 241
- Detachment, 11
- Detachment of particles, 59
- Diffusion, 241
- Diffusional deposition, 79
- Dimensionality, 25
- Dissociation, 25
- DLVO interaction, 0
- Dry particles, 3
- Electrostatic effects, 189
- Electrostatic interactions, 79
- Epitaxy, 373
- Etching, 373
- Fiber networks, 209
- Fiber resuspension, 189
- Gaussian model, 345
- Granular media, 95
- Growth, 373
- Hydrodynamic effects in colloid deposition, 157
- Interaction energy, 115
- Ionic strength, 125
- Irreversible deposition processes, 255
- Irreversible random sequential adsorption, 363
- Iso-electric point, 115
- Lattice site, 325
- Line segments, 363
- Low-energy electron microscopy, 373
- Low-index single crystal surfaces., 373
- Mean spherical model, 345
- Microscopy, 11
- Models of non-equilibrium phenomena, 373
- Nanometer to micrometer size, 3
- Next neighbor exclusion, 345
- Nonequilibrium dynamical models, 231
- Non-uniform flux, 345
- Nucleation, 373
- Numerical solution, 95
- Optical properties, 39
- Oxygen, 373

PII: S0927-7757(99)00534-8

- Packed column technique, 59
- Paper structure, 209
- Particle, 11
- Particle adhesion, 3
- Particle deposition, 0, 95
- Particle relaxation, 325
- Point of zero charge, 115
- Polydispersity, 79
- Protein, 25
- Protein adsorption, 287

- Quantum field representation, 345

- Random deposition, 405
- Random sequential adsorption, 79, 125, 231, 241, 325, 345
- Relaxation, 241
- Removal of adhered particles, 59

- Ruthenium, 373

- Scanning angle reflectometry, 39
- Scanning tunneling microscopy, 373
- Sequential adsorption processes, 287
- Silicon, 373
- Silicone nitride, 115
- Solid substrates, 255
- Spatial correlations, 209
- Spheroidal particle, 0
- Steepest descent ballistic deposition, 405
- Surface element integration, 0
- Surface interactions, 95

- Transient behavior, 95
- Turbulent boundary layer, 189

- Xerography, 11

